

AN14402

使用MCU-Link和LinkServer并行烧写多个目标器件

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应用笔记

文档信息

信息	内容
关键词	AN14402、MCU-Link、LinkServer，烧写多个目标器件
摘要	本文介绍了如何在Windows操作系统环境下并行烧写多个目标器件，从而简化任务并节省时间。



1 概述

一次对多个目标器件进行烧写通常是一项复杂且耗时的任务。本应用笔记介绍了如何使用低成本的MCU-Link和LinkServer调试方案，在Windows平台上对多个目标器件并行烧写，从而简化调试过程并节省时间。

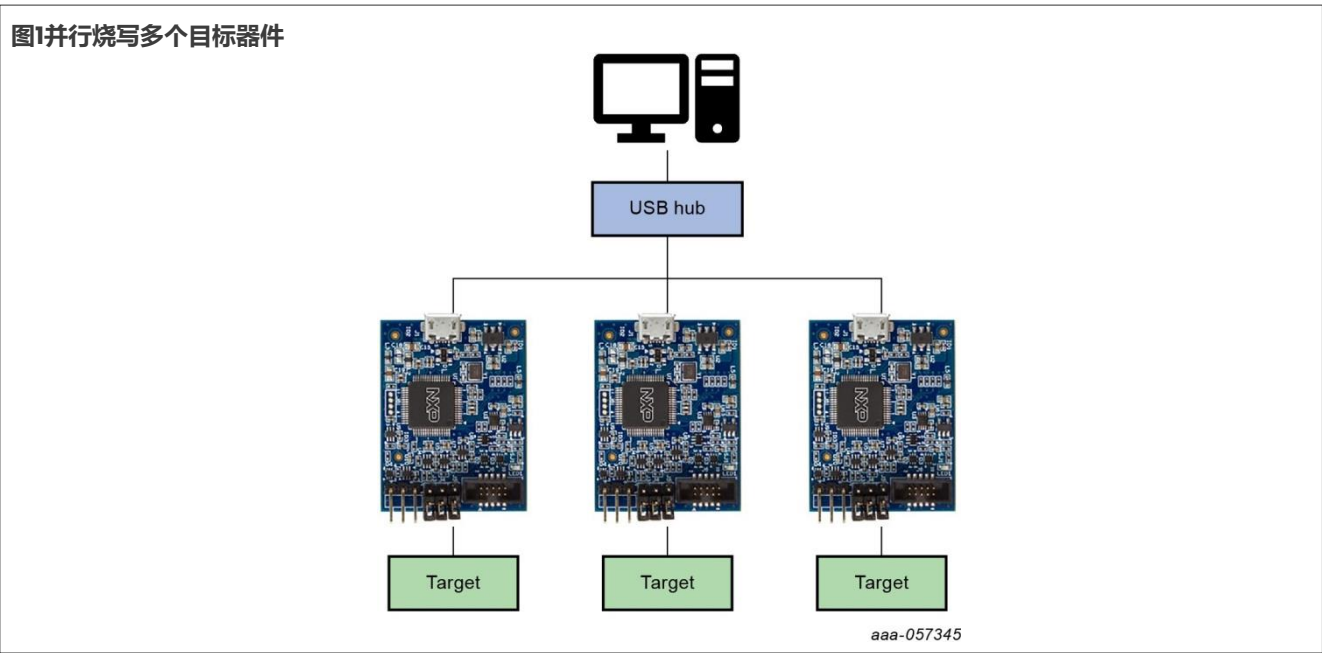
2 系统架构

假设需要同时对三个目标器件进行烧写。

图1所示为并行烧录多个目标器件的系统架构图。每个目标器件都需要搭配一个MCU-Link。

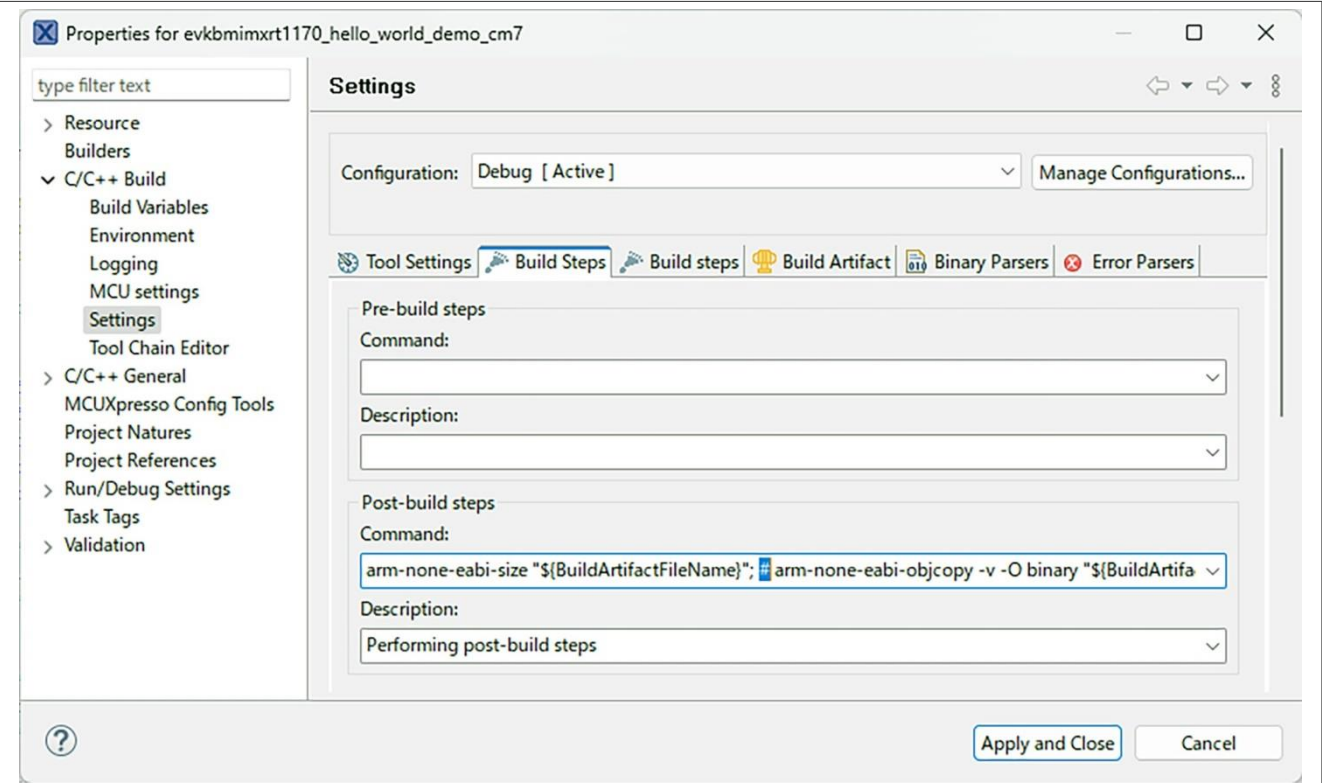
MCU-Link是一款功能强大且经济高效的调试探头，可以无缝地与MCUXpresso-IDE配合使用。MCUXpresso for Visual Studio Code与支持CMSIS-DAP协议的第三方IDE兼容。MCU-Link还包含USB转UART的桥接功能（VCOM），可在目标MCU和主机之间实现串行连接。

在本系统中，主机上的LinkServer可以同时连接三个MCU-Link。LinkServer作为一款GDB服务器管理工具软件，不仅能够启动和管理恩智浦的调试探头，而且具备命令行方式的目标闪存烧写功能。



3 在MCUXpresso IDE中创建二进制映像

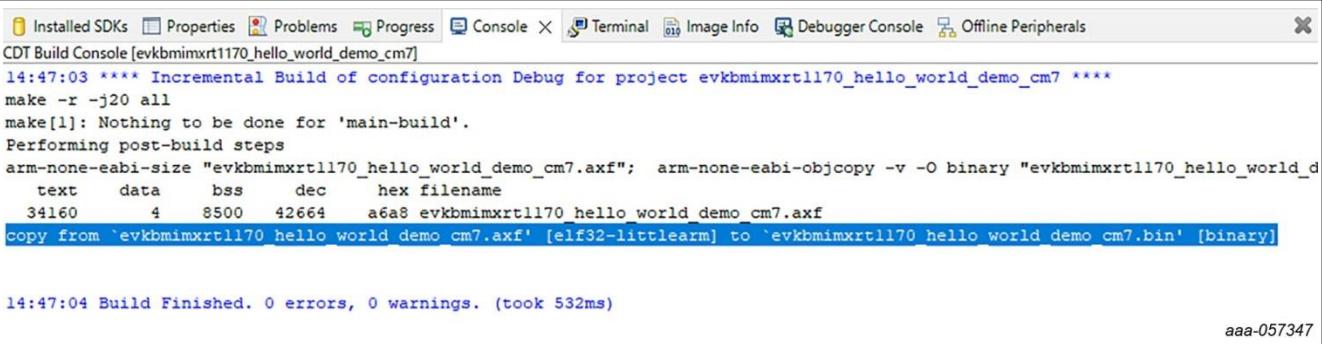
通过MCUXpresso IDE编译生成的二进制映像文件可以直接下载到各个目标器件。为了在构建后直接生成二进制映像文件，可在构建设置中取消对以下命令的注释：`arm-none-eabi-objcopy -v -O binary "${BuildArtifactFileName}" "${BuildArtifactFileName}.bin"`，如图2所示。



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图2 构建后设置

可以确保该二进制映像是由可执行文件生成的，如图3所示。



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图3 由ARM可执行格式文件生成的二进制映像

4 LinkServer脚本

LinkServer需要执行一些脚本来并行处理多个MCU-Link目标器件。本节将介绍本文涉及的两个批处理文件：*program_all_probes.bat*和*program_probe.bat*。

首先，使用一个名为probelist的底层命令来显示连接到主机的所有探头信息：

```
C:\nxp\LinkServer_1.5.30\binaries>redlinkserv --commandline
redlink>probelist
Index = 1
Manufacturer = NXP Semiconductors
Description = MCU-LINK on-board (r0E2) CMSIS-DAP V3.133
```

```
Serial Number = FDNX2FVTNFTVJ
VID:PID = 1FC9:0143
Path = 0002:000a:00
redlink>exit
```

如果想要在主机上识别多个探头中的某一个，请使用该探头对应的序列号。

可以通过识别探头来烧写目标器件。下面给出了一个示例：

```
C:\nxp\LinkServer_1.5.30>LinkServer flash --probe FDNX2FVTNFTVJ MIMXRT1176xxxxx:MIMXRT1170-EVK load
--addr 0x300
00000 C:/Users/<userID>/Downloads/evkbmimxrt1170_hello_world_demo_cm7.bin --erase-all
INFO: Exact match for MIMXRT1176xxxxx:MIMXRT1170-EVK found
INFO: Selected device MIMXRT1176xxxxx:MIMXRT1170-EVK
...
Wc: VTOR = 0x30002000
Wc: Set DEMCR = 0x010007F1
Wc: ===== END SCRIPT =====
```

注：为了优化，可以省略--erase-all。

在批处理文件program_all_probes.bat中，使用probelist来获取各探头的序列号，并以新进程的方式启动批处理文件脚本program_probe.bat。

以下是一个示例脚本：

```
set DOWNLOAD_BIN=./evkbmimxrt1170_hello_world_demo_cm7.bin
set LINKSERVER_BIN=C:/nxp/LinkServer_1.5.30
(
    echo probelist
    echo exit
) | "%LINKSERVER_BIN%/binaries/redlinkserv" --commandline | findstr "Serial Number" >probelist.txt

for /f "tokens=4 delims= " %A in (probelist.txt) do
( echo Probe %A found.
start program_probe.bat %A "%DOWNLOAD_BIN%" %LINKSERVER_BIN%
timeout 3 > nul
)
```

通过运行批处理脚本文件program_probe.bat，可以实现擦除、烧写和验证已识别到的目标器件中的闪存。示例脚本如下所示：

```
%3/LinkServer flash --probe %1 MIMXRT1176xxxxx:MIMXRT1170-EVKB load --addr 0x30000000 %2 --erase-
all > probe_%1.log 2>&1
%3/LinkServer flash --probe %1 MIMXRT1176xxxxx:MIMXRT1170-EVKB verify --addr 0x30000000 %2
>> probe_%1.log 2>&1
exit 0
```

5 运行演示工程

要运行该演示工程，请执行以下步骤：

1. 在主机上安装 LinkServer 1.5.30 版。
2. 使用 USB 线缆将主机与任意数量的 RT1170-EVKB 的 OpenSDA USB 端口连接。
3. 运行批处理文件脚本 program_all_probes.bat。

脚本运行时，会自动检测所有的探头，并打开同样数量的新窗口，如图4所示。

以下是同时连接多个探头的示例脚本：

```
>program_all_probes.bat
Probe F0NU2JRCKEWT found.
Probe FDNX2FVTNFTVJ found.
Probe 0P0NJTEBAJR1G found.
```



图 4. 每个探头都会打开一个新窗口

在完成擦除、烧写和校验操作后，这些窗口会自动关闭。相应的日志会保存在./ probe_{serial number}.log文件中。如果演示工程运行无报错，则表明验证成功。

观察结果：在本实验中，当同时连接三个目标器件时，并行烧录比串行烧写快了约三倍，如[表1](#)所示：

表1. 串行烧录与并行烧录对比

烧录方式	处理时间[s]
串行	424
并行	150

6 结论

MCU-Link与LinkServer可用于并行烧写多个目标器件。这个方案也可以扩展到MacOS或Linux等其他平台。

7 Note about the source code in the document

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8 修订历史

[表2](#)总结了对本文档的修订情况。

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文档编号	发布日期	说明
AN14402 v.1.0	2024年10月18日	首次公开发布

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